



DOCUMENT CHANGE REQUEST

DCR number		1566		Changes required for: General		Originator: Steve Thacker	
Date: 2024/02/12				Date sent: 2023/04/04		Organisation: ESCC Executive Secretariat	
Status: IMPLEMENTED							
Title:		Evaluation Test Programme for Integrated Circuits: Monolithic Microcircuits, Wire-bonded, Plastic					
Number:		2269030		Issue:		1	
Other documents affected:							
25200-4, 9030-2							
Page:							
As per current spec issue above; see also below & attached							
Paragraph:							
See Below							
Original wording:							
As per current spec issue above							
Proposed wording:							
In ESCC 25200: Changes to implement SAM reject criteria per current ESCC9030 Para. 8.6 (& ESCC226903 Para 6.6) in new Para. 7.7: see attached for details (with changes highlighted yellow): i.e. Para. 1.2, 2.1, new Para. 7.7 Additional: ESCC9030 Para. 8.6 & ESCC2269030 Para. 6.6 are amended to remove these same additional reject criteria. see attached for details (with changes highlighted yellow)							
Justification:							
to move the additional reject criteria for plastic encapsulated ICs from ESCC 9030 & 2269030 to 25200 as required by the 9000P Working Group.							

Attachments:
escc9030iss_draft_2a_in_review.docx, escc25200iss_draft_4a_in_review.docx, escc2269030iss_draft_2a_in_review.docx
Modifications:
§7.1 has a typo. It writes “relative chances of the delamination area of more than 10%...” but it actually means “relative changes”.
Approval signature:

Date signed:
2024-02-12